

SPECIFICATION

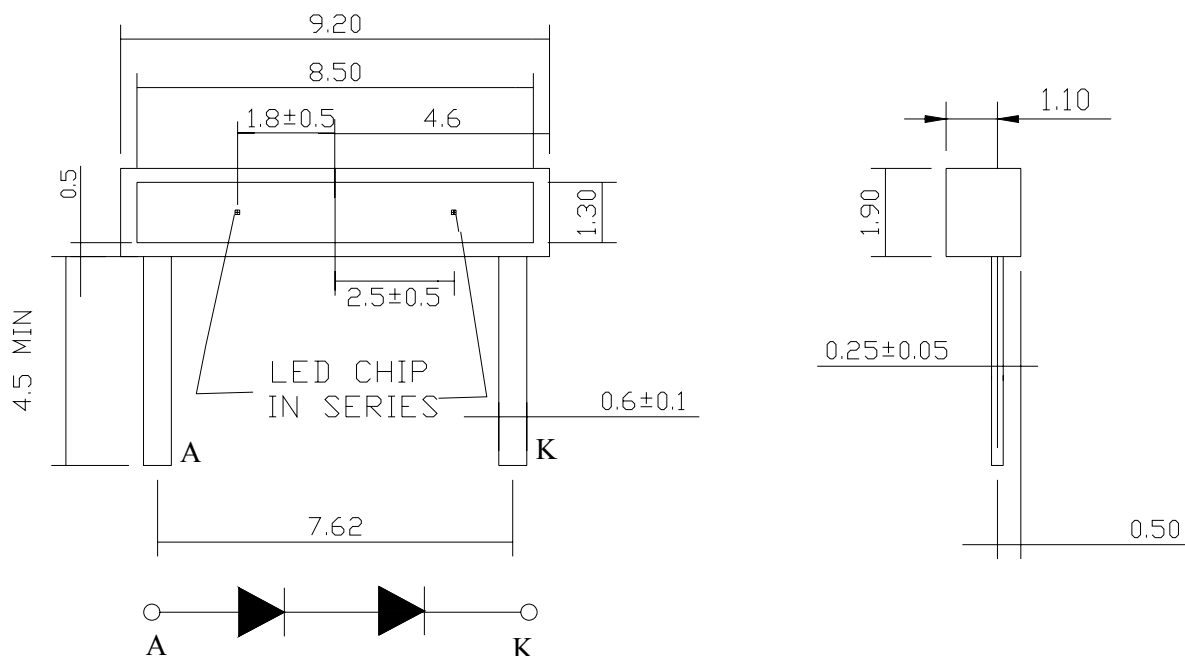
PART NO. : MTBL2410-G-A

1.9 x 9.2mm SIDE VIEW LAMP



ATTENTION
OBSERVE PRECAUTION
FOR HANDLING
ELECTRO STATIC
SENSITIVE
DEVICES

Package Dimensions



Notes:

1. ALL DIMENSIONS ARE IN mm.
2. TOLERANCE IS ± 0.25 mm UNLESS OTHERWISE NOTED.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
MTBL2410-G-A	GaP/GaP	Green	Green Clear

Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	156	mW
Reverse Voltage	V _R	10	V
D.C. Forward Current	I _f	30	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	100	mA
Operating Temperature Range	T _{opr.}	-25 to +85	
Storage Temperature Range	T _{stg.}	-40 to +100	
Lead Soldering Temp. (1.6mm from body) for 5 seconds.		260	

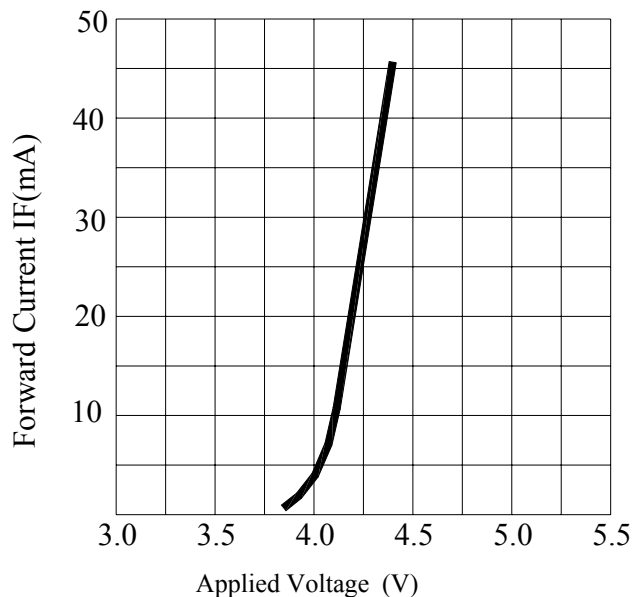
Electrical and Optical Characteristics:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f =20mA	13.5	25		mcd
Forward Voltage	V _f	I _f =20mA		4.2	5.2	V
Peak Wavelength	λ _P	I _f =20mA		567		nm
Dominant Wavelength	λ _D	I _f =20mA		572		nm
Reverse Current	I _r	V _r =10V			100	μA
Viewing Angle	2 θ 1/2	I _f =20mA		50		deg
Spectrum Line Halfwidth	Δλ	I _f =20mA		30		nm

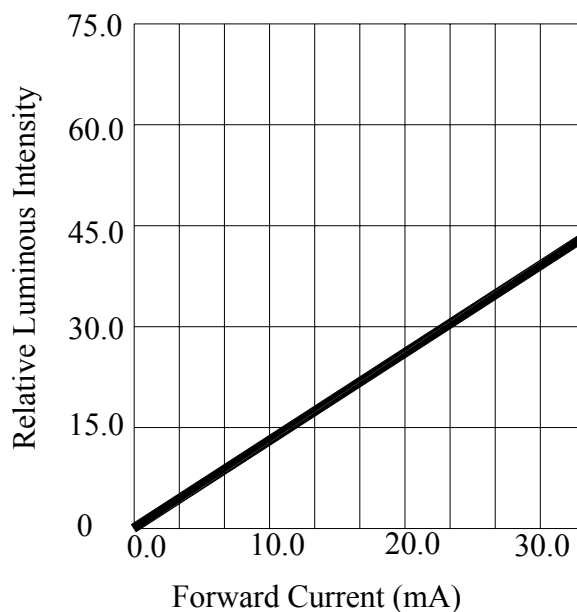
NOTE: THE DATAS TESTED BY IS TESTER

Typical Electrical/Optical Characteristic Curves

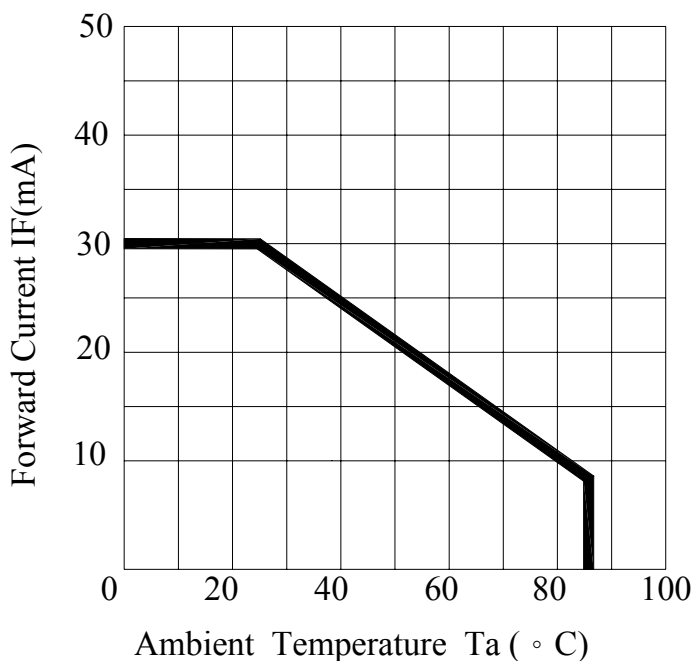
(25 Ambient Temperature Unless Otherwise Noted)



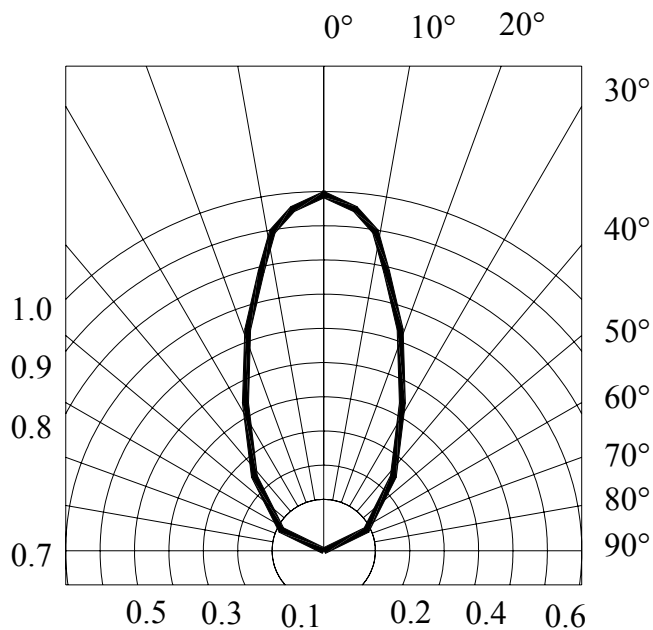
Forward Current VS. Applied Voltage



Forward Current VS. Luminous Intensity



Ambient Temperature vs. Forward Current



Radiation Diagram

PRECAUTION IN USE

Storage

Recommended storage environment

Temperature: 5°C ~ 30°C (41°F ~ 86°F)

Humidity: 60% RH Max.

Use within 3 days after opening of sealed vapor/ESD barrier bags.

Fold the opened bag firmly and keep in dry environment.

Soldering

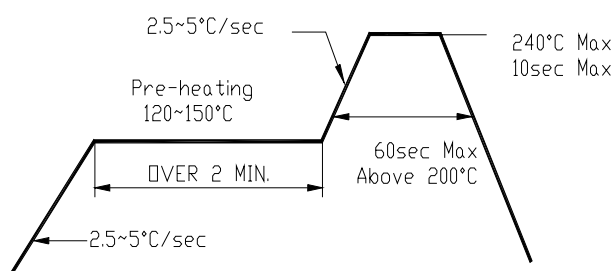
	Reflow Soldering		Hand Soldering	
	Lead Solder	Lead – free Solder	Temperature Soldering time	350 Max 3sec Max (one time only)
Pre-heat	120~150	180~200		
Pre-heat time	120sec Max	120sec Max		
Peak temperature	240 Max	260 Max		
Soldering time Condition	10sec Max refer to Temperature- profile 1	10sec Max refer to Temperature- profile 2		

*After reflow soldering rapid cooling should be avoided.

[Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.

< 1 : Lead Solder >



< 2 : Lead-free Solder >

